

# APPENDIX D

**(MARKED-UP VERSION OF CLAIMS)**

**(Serial No. 09/652,495)**

APPENDIX D

**Version of Claims with markings to show changes made**

3. (Amended) The chip-scale package of claim 1, wherein said at least one electrically conductive via extends substantially directly through said semiconductor substrate.

4. (Amended) The chip-scale package of claim 1, further comprising a substantially laterally extending conductive trace in communication with said at least one electrically conductive via.

42. (Amended) The chip-scale package of claim 21, further comprising a conductive trace extending substantially laterally from said corresponding via.

43. (Amended) A flip-chip carrier, comprising a [silicon]semiconductor substrate including at least one via formed therethrough and positioned to substantially align with a corresponding bond pad of a semiconductor device to be assembled with said semiconductor substrate.

51. (Amended) The flip-chip carrier of claim 43, further comprising a conductive bump disposed adjacent an end of said at least one via.